出國報告(出國類別:發表論文)

出席環球學術集群北海道國際冬季會議及發表論文

服務機關:國立高雄師範大學

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派赴國家:日本

出國期間:105年2月20日至24日

報告日期:105年3月15日

摘要

本次出國主要參加在日本北海道札幌市舉辦的環球學術集群北海道國際冬季會議 (Universal Academic Cluster International Winter Conference in Hokkaido),並發表論文: 具有及無摻雜通道之鋁氮化鎵/氮化鎵高電子遷移率電晶體的比較(Comparison of AlGaN/GaN high electron mobility transistors with and without doping-channel layers)。此 會議是在日本北海道舉辦的國際專業研討會,本人所發表論文主要探討奈米半導體元件之技術,參與人員皆來自各方菁英。與會期間除了論文展示時間在場解說外,也積極到各場次聆聽演講、交流資訊,此對於本實驗室對外發展與未來研究具正面意義。

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1. 目的

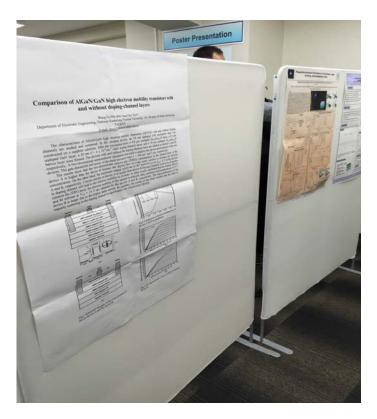
本人此次赴日本札幌市出席環球學術集群北海道國際冬季會議,並發表論文:具有及無摻雜通道之鋁氮化鎵/氮化鎵高電子遷移率電晶體的比較(Comparison of AlGaN/GaN high electron mobility transistors with and without doping-channel layers)。出席該國際學術會議的主要目的為論文發表,分享研究成果,並與國內外相關研究領域的學者意見交流。



舉辦地點-北海道大學旁之札幌公務員受驗學院大樓內

2. 參加會議過程

此次會議本人於 105 年 2 月 20 日由高雄搭機直飛日本札幌。2 月 22 日前往會場報到,領取名牌、會議資料等。2 月 23 日發表研究論文。會議期間根據會議資料,選取相關領域的報告會議參與。會議期間至北海道大學參觀。最後於 2 月 24 日回國。本次國際會議由環球學術集群(Universal Academic Cluster)主辦。本次會議地點於北海道大學旁之札幌公務員受驗學院大樓內舉行。此次會議約有40餘篇論文發表,其會議論文品質及原創性極高。本人發表一篇論文,屬於科學與技術(Science and Technology)領域,並與參與學者交換研究心得。所發表論文主題為:Comparison of AlGaN/GaN high electron mobility transistors with and without doping-channel layers。對於此篇論文,主要是在 鋁氮化鎵/氮化鎵異質接面加入一20奈米 n型濃度為 4 x 10¹⁷cm⁻³的氮化鎵層,已和較傳未具有該層之元件相比較。我們的結果顯示,n型氦化鎵層的元件具有較高的電子濃度,然而其最大電流密度與轉導值卻皆降低。此是因這n型氦化鎵有高的雜質散射,而造成鋁氦化鎵/氦化鎵異質接面之電子遷移率降低。會議中與會學者對本人發表之論文深感興趣,特別是韓國學者,且針對高電子遷移率電品體特性提供多項寶貴意見。



展示會場



參觀北海道大學

3. 心得及建議

- (1) 所參與之領域中,學者們對於高電子遷移率電晶體元件與半導體材料方面有優異之研究成果,且展示其研究方法及過程。
- (2) 與會過程中有兩篇關於發光電化學電池(Light-Emitting Electrochemical Cells)與深藍電激光(Deep blue electroluminescence)之論文發表,本人對於其利用光敏材料(如phenanthroimidazole)衍生物與離子分子達到發光效果,而該論文對於發光機制與製造方法探討詳盡。而此雖與吾人最近製作的半導體發光二極體結構與機制不同,此可以增進元件發展方向與應用範疇。
- (3) 對於主辦單位熱情接待及與會學者熱烈討論印象深刻。
- (4) 本國應多舉辦半導體元件與材料相關之國際學術會議,使各國學者對我國之研究環境及成果有深刻認識,並可提升我國研究之質與量。

4. 攜回資料



研討會資料

Comparison of AlGaN/GaN high electron mobility transistors with and without doping-channel layers

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The characteristics of AlGaN/GaN high electron mobility transistors (HEMTs) with and without doping channels are studied and compared. In the studied devices, an 18 nm undoped AlN nucleation layer was constructed on a sapphire substrate. After the nucleation layer, a 0.8 μ m undoped Al $_{0.38}$ Ga $_{0.62}$ N layer, a 0.4 μ m undoped GaN layer, a 20 nm n $^{+}$ = 4 x 10 17 cm $^{-3}$ GaN doping-channel layer, and a 30 nm undoped Al $_{0.38}$ Ga $_{0.62}$ N barrier layer were formed. The devices with and without the doping-channel layer are labeled as devices A and B, respectively. A two-dimensional semiconductor simulation was used to analyze the device performance of the two devices. The gate dimension and spacer of the drain-to-source were 1 × 100 μ m 2 and 3 μ m, respectively.

The results show that the two-dimensional electron gas (2DEG) concentration in the channel layer of the device A is higher than the device B because the doping layer provides more carriers to increase the electron concentration. On the other hand, the maximum output current are of 487 and 639 mA at $V_{\rm GS}=6$ V in the devices A and B, respectively. Current density of device A is smaller than device B because impurity scattering of carriers in doping channel will lead to the electron mobility to decrease. In other words, attributed that the doping channel contacts the 2DEG layer, the electron mobility of the channel is reduced. Also, extrinsic transconductances of 57.7 and 84 mS/mm at $V_{\rm DS}=14$ V are obtained for the devices A and B, respectively. The transconductance of the device B is larger due to the higher drain current. In summary, the results of this study exhibits that the effect of impurity scattering in the doping channel is significant in the AlGaN/GaN HEMTs.

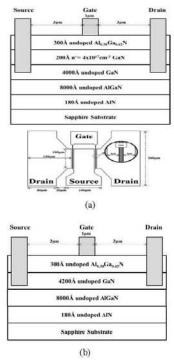


Fig.1 Schematic diagram of the cross sections of the (a) device A and (b) device B.

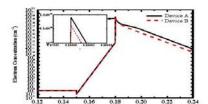


Fig. 2. Comparison of electron concentrations of devices A and B at equilibrium.

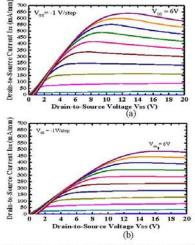


Fig.3. I-V characteristics of the (a) device A and (b) device B.